

### Typical Applications

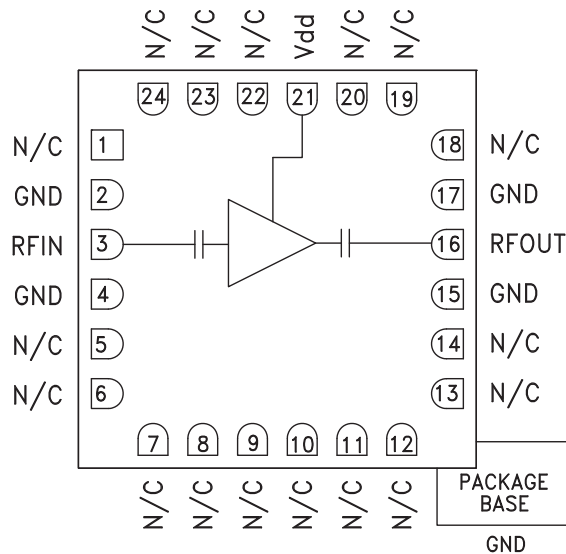
The HMC342LC4 is ideal for:

- Point-to-Point Radios
- Point-to-Multi-Point Radios & VSAT
- Test Equipment & Sensors
- Military End-Use

### Features

- Noise Figure: 3.5 dB
- Gain: 22 dB
- Single Positive Supply: +3V @ 43 mA
- 50 Ohm Matched Input/Output
- RoHS Compliant 4x4 mm SMT Package

### Functional Diagram



### General Description

The HMC342LC4 is a GaAs PHEMT MMIC Low Noise Amplifier housed in a leadless 4x4 mm RoHS compliant SMT package. Operating from 13 to 25 GHz, the amplifier provides 22 dB of gain and +19 dBm of output IP3 from a single +3V supply. The low noise figure performance of 3.5 dB is ideal for receive and transmit pre-driver applications. The RF I/Os are DC blocked and matched to 50 Ohms for ease of use. The HMC342LC4 allows the use of surface mount manufacturing techniques and requires no external matching components.

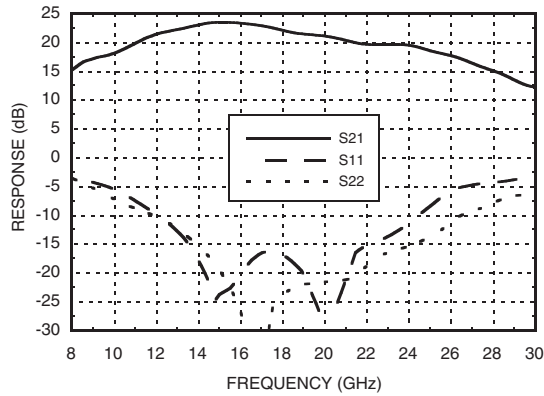
### Electrical Specifications, $T_A = +25^\circ C$ , $V_{dd} = +3V$ , $I_{dd} = 43 mA$

| Parameter                                | Min.    | Typ.  | Max.  | Min.    | Typ.  | Max.  | Min.    | Typ.  | Max.  | Units  |
|--|---------|-------|-------|---------|-------|-------|---------|-------|-------|--------|
| Frequency Range                          | 13 - 18 |       |       | 18 - 22 |       |       | 22 - 25 |       |       | GHz    |
| Gain                                     | 19      | 22    |       | 17      | 20    |       | 16      | 19    |       | dB     |
| Gain Variation Over Temperature          |         | 0.025 | 0.035 |         | 0.025 | 0.035 |         | 0.025 | 0.035 | dB/ °C |
| Noise Figure                             |         | 3.5   | 4.0   |         | 3.5   | 4.0   |         | 3.5   | 4.5   | dB     |
| Input Return Loss                        |         | 15    |       |         | 15    |       |         | 10    |       | dB     |
| Output Return Loss                       |         | 15    |       |         | 20    |       |         | 15    |       | dB     |
| Output Power for 1 dB Compression (P1dB) |         | 7     |       |         | 8     |       |         | 9     |       | dBm    |
| Saturated Output Power (Psat)            |         | 9     |       |         | 11    |       |         | 11.5  |       | dBm    |
| Output Third Order Intercept (IP3)       |         | 16    |       |         | 19    |       |         | 20    |       | dBm    |
| Supply Current (Idd) (Vdd = +3V)         |         | 43    |       |         | 43    |       |         | 43    |       | mA     |

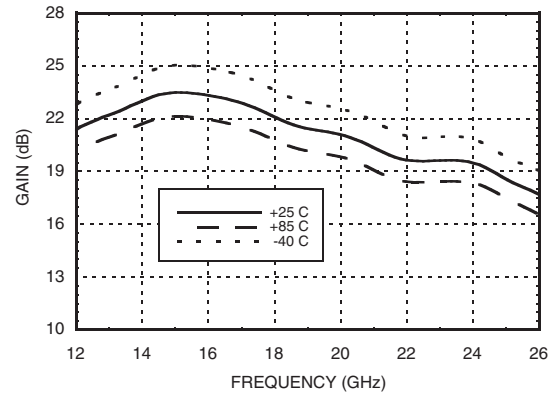


**GaAs PHEMT MMIC LOW NOISE  
AMPLIFIER, 13 - 25 GHz**

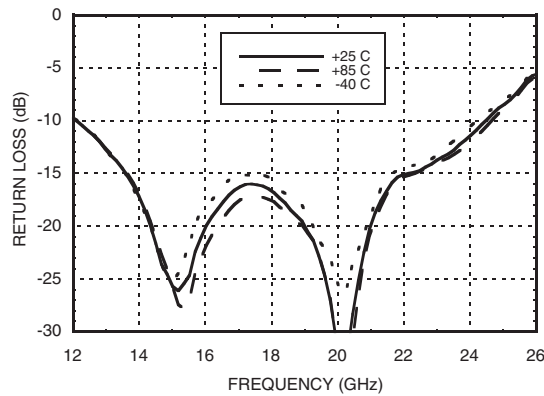
**Broadband Gain & Return Loss**



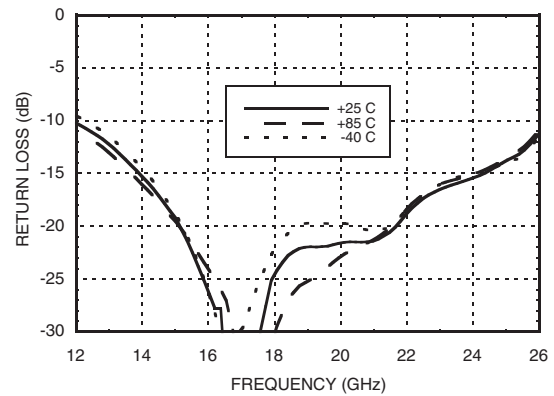
**Gain vs. Temperature**



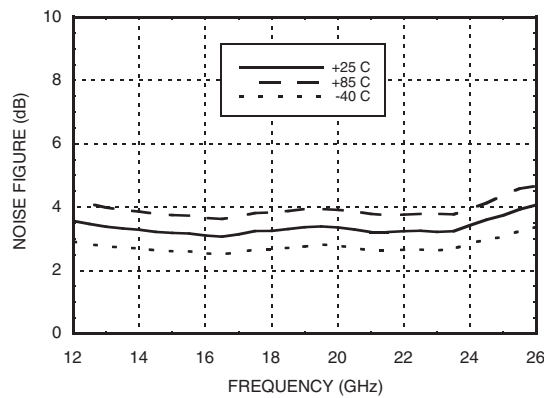
**Input Return Loss vs. Temperature**



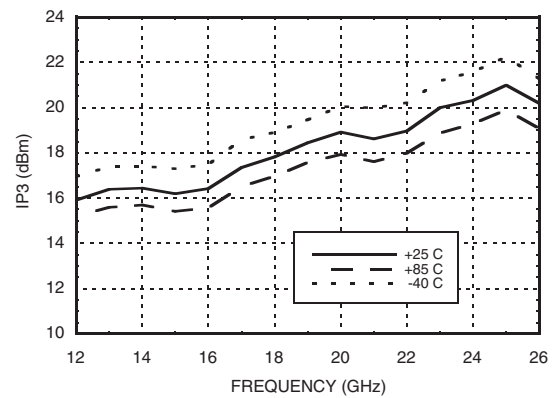
**Output Return Loss vs. Temperature**



**Noise Figure vs. Temperature**



**Output IP3 vs. Temperature**



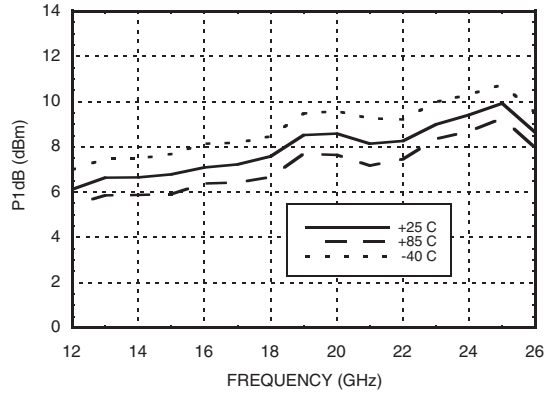
## GaAs PHEMT MMIC LOW NOISE AMPLIFIER, 13 - 25 GHz



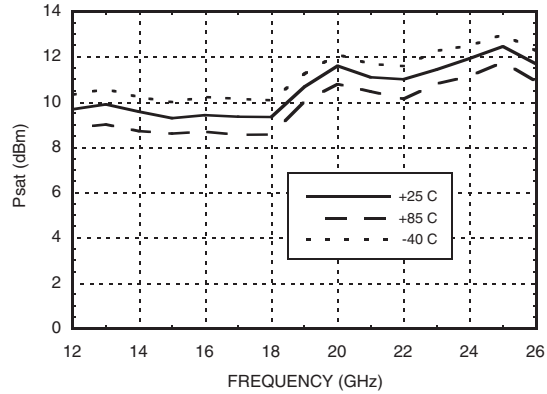
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LOW NOISE AMPLIFIERS - SMT

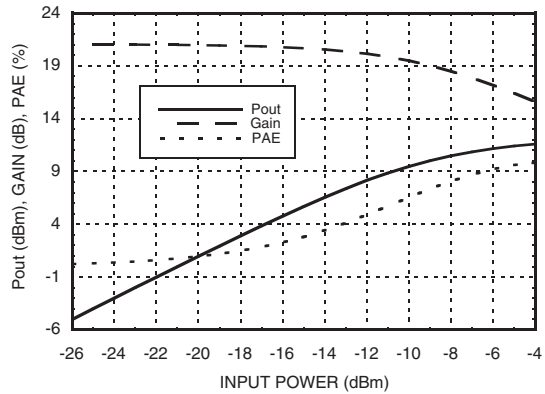
**P1dB vs. Temperature**



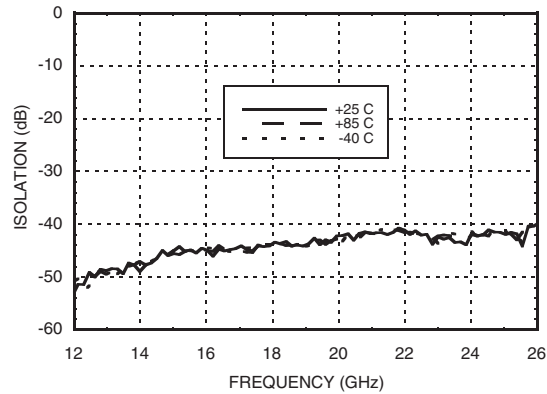
**Psat vs. Temperature**



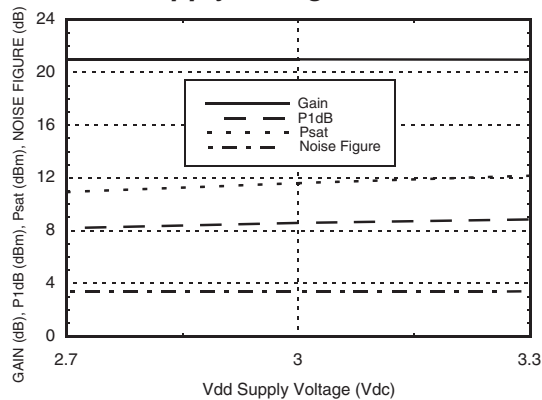
**Power Compression @ 20 GHz**



**Reverse Isolation vs. Temperature**



**Gain, Power & Noise Figure vs. Supply Voltage @ 20 GHz**



### Absolute Maximum Ratings

|  |                |
|--|----------------|
| Drain Bias Voltage (Vdd)                                       | +5.5 Vdc       |
| RF Input Power (RFIN)(Vdd = +3.0 Vdc)                          | 0 dBm          |
| Channel Temperature  | 175 °C         |
| Continuous Pdiss (T= 85 °C)<br>(derate 3.62 mW/°C above 85 °C) | 0.326 W        |
| Thermal Resistance<br>(channel to ground paddle)               | 276 °C/W       |
| Storage Temperature  | -65 to +150 °C |
| Operating Temperature  | -40 to +85 °C  |

### Typical Supply Current vs. Vdd

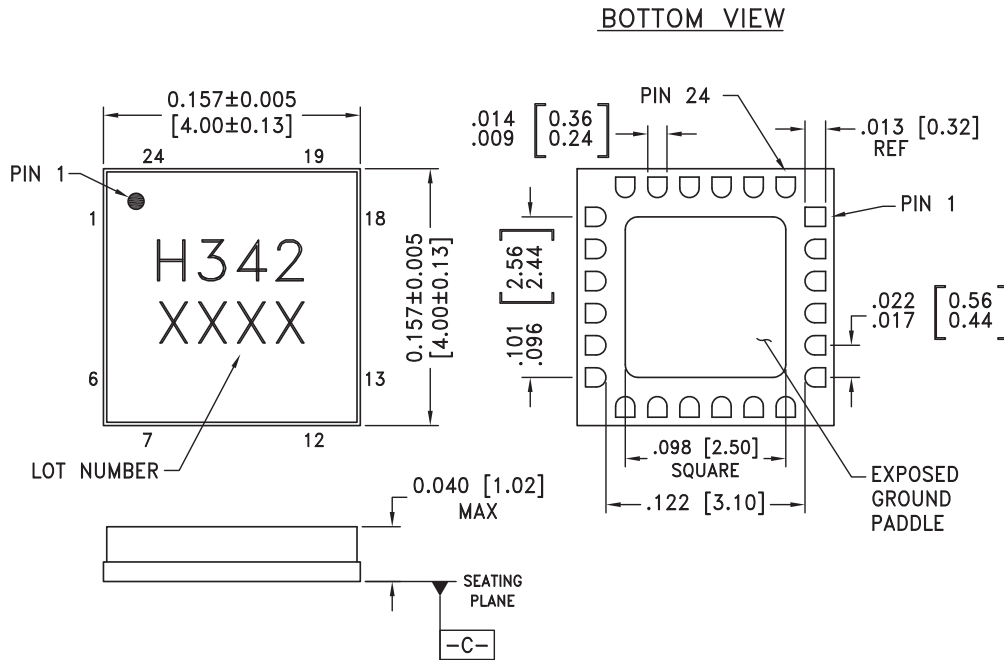
| Vdd (Vdc) | Idd (mA) |
|-----------|----------|
| +2.7      | 42       |
| +3.0      | 43       |
| +3.3      | 44       |

Note: Amplifier will operate over full voltage ranges shown above.



ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS


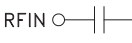
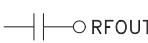

### Outline Drawing



NOTES:

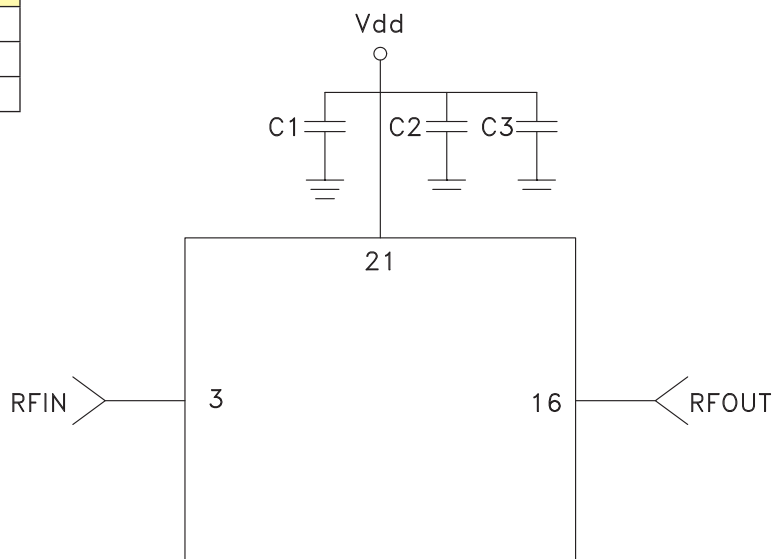
1. PACKAGE BODY MATERIAL: ALUMINA.
2. LEAD AND GROUND PADDLE PLATING: GOLD FLASH OVER NICKEL.
3. DIMENSIONS ARE IN INCHES (MILLIMETERS).
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
5. PACKAGE WARP SHALL NOT EXCEED 0.05MM DATUM [-C-]
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

**Pin Descriptions**

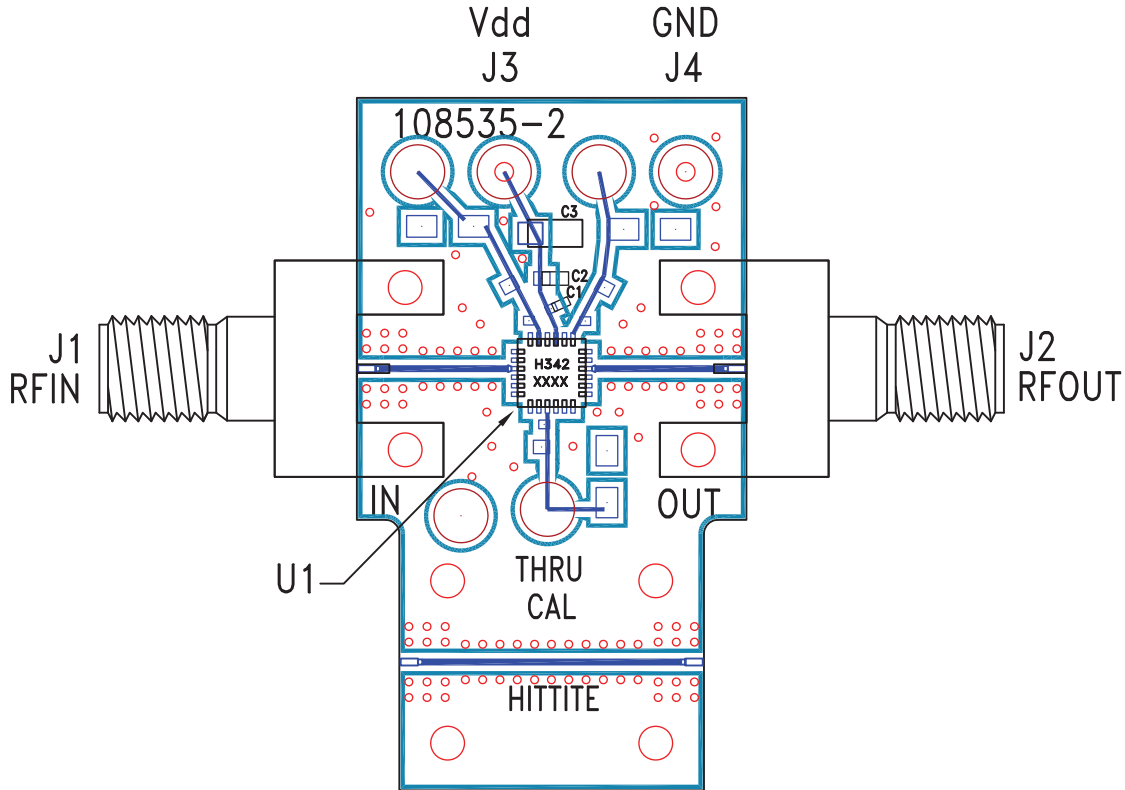
| Pin Number                     | Function | Description  | Interface Schematic   |
|--------------------------------|----------|--|---|
| 1, 5 - 14,<br>18 - 20, 22 - 24 | N/C      | No connection required. These pins may be connected to RF/DC ground without affecting performance.             |   |
| 2, 4, 15, 17                   | GND      | Package base has an exposed metal ground that must also be connected to RF/DC ground.                          |  |
| 3                              | RFIN     | This pin is AC coupled and matched to 50 Ohms.   |  |
| 16                             | RFOUT    | This pin is AC coupled and matched to 50 Ohms.   |  |
| 21                             | Vdd      | Power Supply Voltage for the amplifier. External bypass capacitors of 100 pF, 1000pF, and 2.2 μF are required. |  |

**Application Circuit**

| Component | Value    |
|-----------|----------|
| C1        | 100 pF   |
| C2        | 1,000 pF |
| C3        | 2.2 μF   |



### Evaluation PCB



### List of Materials for Evaluation PCB 110209 [1]

| Item    | Description                   |
|---------|-------------------------------|
| J1, J2  | 2.92 mm PC mount K-connector  |
| J3, J4  | DC Pin                        |
| C1      | 100 pF capacitor, 0402 pkg.   |
| C2      | 1,000 pF Capacitor, 0603 pkg. |
| C3      | 2.2μF Capacitor, Tantalum     |
| U1      | HMC342LC4 Amplifier           |
| PCB [2] | 108535 Evaluation PCB         |

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350.

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.